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Aehr Test Systems Receives Upgrade Order for FOX-XP™ Test and Burn-in System for Silicon Photonics Devices

Fremont, CA (September 6, 2017) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received a $900,000 order from one of its lead FOX-XP Test and Burn-in System customers to provide additional test capability and power handling capacity to their FOX-XP system in order to meet that customer's new device requirements.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, "We are excited to receive this upgrade order to the FOX-XP production system previously delivered to this customer a few months ago. This order is part of a previously discussed plan for this customer to upgrade and add capability to the system to test and burn-in devices used in server backplane and storage communications applications. The upgrade improves not only the testing capability for this application by increasing the voltage capability of each of the tester channels, it also increases the power handling capability of the customer's configuration from 1,000 watts to 2,000 watts per wafer. Importantly, we believe that this upgrade enhances the FOX-XP system's capability and cost-effectiveness for high volume wafer level test and burn-in of the customer's current and next generation devices."

The FOX-XP system, available in multi-wafer and singulated die/module test configurations, is capable of functional test and burn-in/cycling of integrated optical devices, 2D and 3D sensors, magnetic sensors, flash memories, microcontrollers, and other leading-edge ICs in either wafer form, before they are assembled into single or multi-die stacked packages, or in singulated die/module form. A single FOX-XP test system may be configured with up to 18 blades of wafer test resources, enabling up to 18 wafers to be tested simultaneously handling 1 kW or nine wafers at up to 2 kW per wafer. Each slot may be configured with up to eight Universal Channel Channel Modules (UCCMs), High Current Channel Modules (HCCMs), or High Voltage Channel Modules (HVCMs) to supply device stimulus to test/burn-in/cycle die or modules. The footprint of the 18-wafer test system is similar to the footprint of typical semiconductor Automatic Test Equipment (ATE) that can only test one wafer at a time.

The FOX-XP system utilizes Aehr Test's FOX WaferPak™ contactor, which provides a cost-effective solution for making full wafer electrical die contact in a multi-wafer environment. Aehr Test's WaferPak contactors contain up to tens of thousands of probes to contact all die simultaneously on wafers and substrates up to 300mm. Another key component of the FOX-XP system is the FOX WaferPak Aligner, which provides fully automatic alignment of the customer's wafers to the WaferPak contactor.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS and FOX-P™ families of test and burn-in systems, the FOX WaferPak™ Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP™ system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak Contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak Contactor technologies, acceptance by ustomers of the FOX-XP system, WaferPak Aligners and WaferPak Contactors shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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